

# **Vapor Chamber**

#### **Features**

- · Horizontally conduction
- Passive components
- High stability
- · Efficiency higher than heat pipe 10 times

## **Applications**

Best for high power applications

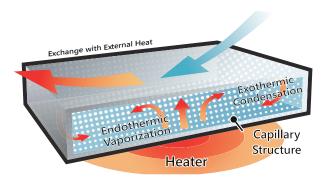
Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED, Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device, Wireless Hub, DDR II Module, etc.

### **Properties**

Item	VC001	VC002	VC003	XVC-A001	XVC-A002	Unit	Tolerance
Size	56×56	106×70	106×70	90×60	80×80	mm	±0.3
Thickness	3.0	3.0	25.5	0.4	0.4	mm	±0.05
Thermal Resistance	≦ 0.21	≦ 0.16	≦ 0.16	<0.02	<0.02	° C/W	-
Material	Pure copper			Copper alloy		-	-
Surface finishing	anti-oxidation					-	-
Extra components	-	-	copper heat sink	-	-	-	-
Operation Power (Qmax)	≥110	≥150	≥150	10	10	W	-
Image				\$7		-	-

▶ Different industries will require different specifications, please contact us direcly for the most suitable specifications.

#### Mechanism



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T-Global Technology are proud to announce the launch of a new company logo and mission statement as part of the ongoing growth and evolution of our company's brand.